

LOADING DIP (DUAL IN-LINE PACKAGE) DEVICES

Most DIP devices have their leads spread so that they can not be dropped straight into the board. They must be "walked in" using the following procedure:

- (1) Orient the device properly. Pin 1 is indicated by a small embossed dot on the top surface of the device at one corner. Pins are numbered counterclockwise from pin 1.
- (2) Insert the pins on one side of the device into their holes on the printed circuit card. Do not press the pins all the way in, but stop when they are just starting to emerge from the opposite side of the card.
- (3) Exert a sideways pressure on the pins at the other side of the device by pressing against them where they are still wide below the bend. Bring this row of pins into alignment with its holes in the printed circuit card and insert them an equal distance, until they begin to emerge.
- (4) Press the device straight down until it seats on the points where the pins widen.
- (5) Turn the card over and select two pins at opposite corners of the device. Using a fingernail or a pair of long-nose pliers, push these pins outwards until they are bent at a 45° angle to the surface of the card. This will secure the device until it is soldered.

SOLDERING TIPS

- (1) Use a low-wattage iron--25 watts is good. Larger irons run the risk of burning the printed-circuit board. Don't try to use a soldering gun, they are too hot.
- (2) Use a small pointed tip and keep it clean. Keep a damp piece of sponge by the iron and wipe the tip on it after each use.
- (3) Use 60-40 rosin-core solder ONLY. DO NOT use acid-core solder or externally applied fluxes. Use the smallest diameter solder you can get.

NOTE: DO NOT press the top of the iron on the pad or trace. This will cause the trace to "lift" off of the board which will result in permanent damage.

- (4) In soldering, wipe the tip, apply a light coating of new solder to it, and apply the tip to both parts of the joint, that is, both the component lead and the printed-circuit pad. Apply the solder against the lead and pad being heated, but not directly to the tip of the iron. Thus, when the solder